

## 层压叠构要求(Stack Up Requirement)

客户代码(Cust. Code): U03

编写(Prepared by): 张晓乐

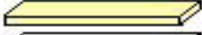






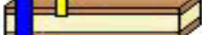

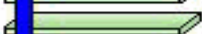














明阳编号(Internal P/N): HCGU03060C0

审核(Approval pending):

客户编号(Cust. P/N): 000-0005200 Rev. A2

QAE(QAE):
















层序	层属性	基铜	覆铜率%	物料图片描述	物料类型	介电常数 (1GHz)	Pressed Thk 压合后厚度(Mil)	Pressed Thk 压合后厚度(mm)
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Lyr	Type	Foil	CU %	Image	Generic Name	Family	Er	THK_MIL	THK_MM
spt									
sst									
smt									
I1	Sig	0.33oz	54		Foil Toz	HuiRu	0.00	0.472	0.012
					1080HR RC68	S1000-2B	4.02	2.959	0.075
I2	PG	0.5oz	75		Foil Hoz	HuiRu	0.00	1.362	0.035
					2116 RC54	S1000-2B	4.39	3.734	0.095
I3	Sig	1oz	24		Core 0.115 MM 1/1 W/O Cu	S1000-2	4.31	7.071	0.18
I4	PG	1oz	75		1080 RC64	S1000-2B	4.09		
					1080 RC64	S1000-2B	4.09	4.694	0.119
I5	Sig	1oz	27		Core 0.10 MM 1/1 W/O Cu	S1000-2	4.34	6.48	0.165
I6	PG	1oz	73		106 RC74	S1000-2B	3.92		
					106 RC74	S1000-2B	3.92	3.261	0.083
I7	PG	1oz	74		Core 0.10 MM 1/1 W/O Cu	S1000-2	4.34	6.48	0.165
I8	Sig	1oz	28		1080 RC64	S1000-2B	4.09		
					1080 RC64	S1000-2B	4.09	4.706	0.12
I9	PG	1oz	75		Core 0.115 MM 1/1 W/O Cu	S1000-2	4.31	7.071	0.18
I10	Sig	1oz	24		2116 RC54	S1000-2B	4.39	3.734	0.095
I11	PG	0.5oz	75		Foil Hoz	HuiRu	0.00	1.362	0.035
					1080HR RC68	S1000-2B	4.02	2.959	0.075
I12	Sig	0.33oz	25		Foil Toz	HuiRu	0.00	0.472	0.012
smb									
ssb									
spb									

Requirement 要求	Req. Thickness 要求厚度(inch)	Req. Thickness 要求厚度(mm)	Tol (+/-) 公差(Inch)	Tol (+/-) 公差(mm)	Calculate Thick 计算厚度(Inch)	Calculate Thick 计算厚度(mm)
Incl. Plating&Mask 成品板厚(含电镀和阻焊)	0.062000	1.574800	+ 0.0062/- 0.0062	+ 0.157/- 0.157	0.061300	1.557300
After Lamination 压合后板厚	0.057500	1.459800	+ 0.0057/- 0.0057	+ 0.145/- 0.145	0.056800	1.442300

备注(Note): Sig=Signal PG=Power/Ground Blk=Blank(Foil Etched); W/ = With W/O = WithOut ;

# 阻抗控制要求 (Impedance Requirement)

Index 次序	Layer 层别	Group 组别	Ref Layer 参考层			Customer Design 客户设计						Calculation Result 计算后值					Unit: mil
			Up 上	Down 下	Self 当前	Imp. Mode 阻抗模型	Target Imp. 成品阻抗Ω	Tolerance 公差(±Ω)	Line Width 成品线宽	Space 成品线距	L 2 Cu 线2铜	Line Width 调整线宽	Space 调整线距	L 2 Cu 线2铜	Calculated 计算阻抗Ω	Remark 备注	
1	L01	A		L2		 se_coated_microstrip	50.00	5.00	4.720	—	—	4.500	—	—	49.55		
2	L01	G		L2		 diff_coated_microstrip	90.00	9.00	5.000	9.000	—	4.800	9.200	—	89.73		
3	L01	K		L2		 diff_coated_microstrip	100.00	10.00	4.000	10.000	—	3.900	10.100	—	99.05		
4	L03	C	L4	L2		 se_stripline	50.00	5.00	3.700	—	—	3.000	—	—	49.05		
5	L03	I	L4	L2		 diff_stripline	90.00	9.00	4.500	10.000	—	3.650	10.850	—	89.01		
6	L03	M	L4	L2		 diff_stripline	100.00	10.00	3.700	12.000	—	2.850	12.850	—	99.56		
7	L05	D	L6	L4		 se_stripline	50.00	5.00	3.700	—	—	3.300	—	—	49.03		
8	L05	N	L6	L4		 diff_stripline	100.00	10.00	3.700	12.000	—	3.150	12.550	—	99.18		
9	L08	E	L7	L9		 se_stripline	50.00	5.00	3.700	—	—	3.300	—	—	49.06		
10	L10	F	L9	L11		 se_stripline	50.00	5.00	3.700	—	—	3.000	—	—	49.05		
11	L10	J	L9	L11		 diff_stripline	90.00	9.00	4.500	10.000	—	3.650	10.850	—	89.01		
12	L10	O	L9	L11		 diff_stripline	100.00	10.00	3.700	12.000	—	2.850	12.850	—	99.56		
13	L12	B		L11		 se_coated_microstrip	50.00	5.00	4.720	—	—	4.500	—	—	49.55		
14	L12	H		L11		 diff_coated_microstrip	90.00	9.00	5.000	9.000	—	4.800	9.200	—	89.73		
15	L12	L		L11		 diff_coated_microstrip	100.00	10.00	4.000	10.000	—	3.900	10.100	—	99.05		

备注 (Note): L 2 Cu=line to Cu of Ground which is applied for the coplanar strips.